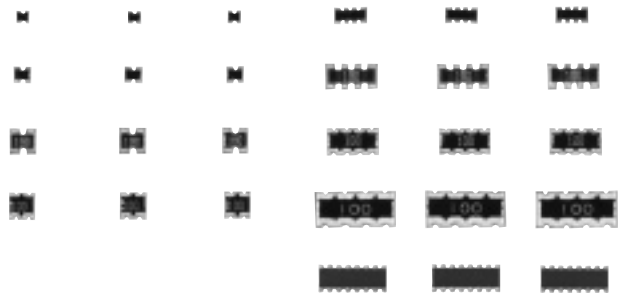


Chip Resistor Array

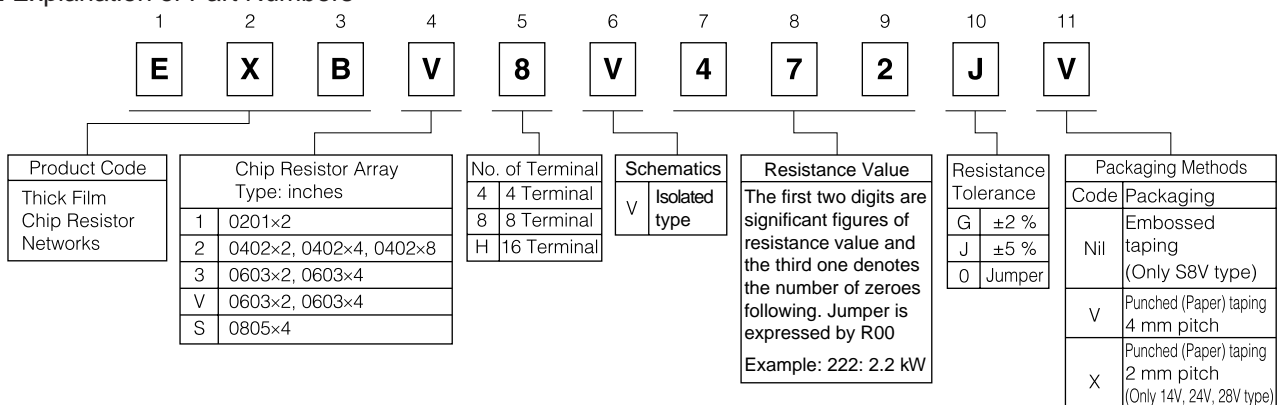
Type: **EXB1:0201x2**
EXB2:0402x2, 0402x4, 0402x8
EXB3:0603x2, 0603x4
EXBV:0603x2, 0603x4
EXBS:0805x4



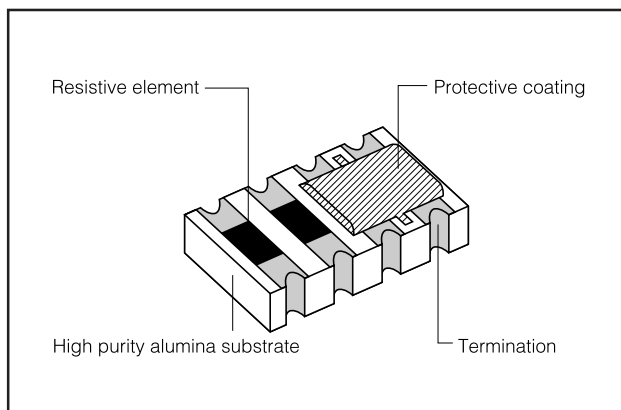
■ Features

- High density
 - 2 resistors in 0.8 mm × 0.6 mm size (14V, Convex Terminal)
 - 2 resistors in 1.0 mm × 1.0 mm size (24V, Convex Terminal)
 - 2 resistors in 1.6 mm × 1.6 mm size (34V, Convex Terminal)
 - 2 resistors in 1.6 mm × 1.6 mm size (V4V, Concave Terminal)
 - 4 resistors in 2.0 mm × 1.0 mm size (28V, Convex Terminal)
 - 4 resistors in 3.2 mm × 1.6 mm size (38V, Convex Terminal)
 - 4 resistors in 3.2 mm × 1.6 mm size (V8V, Concave Terminal)
 - 4 resistors in 5.08 mm × 2.2 mm size (S8V, Concave Terminal)
 - 8 resistors in 3.8 mm × 1.6 mm size (2HV, Convex Terminal)
- Improvement of placement efficiency
 Placement efficiency of Chip Resistor Array is two, four or eight times of the flat type chip resistor
- Approved under the ISO 9001 system

■ Explanation of Part Numbers

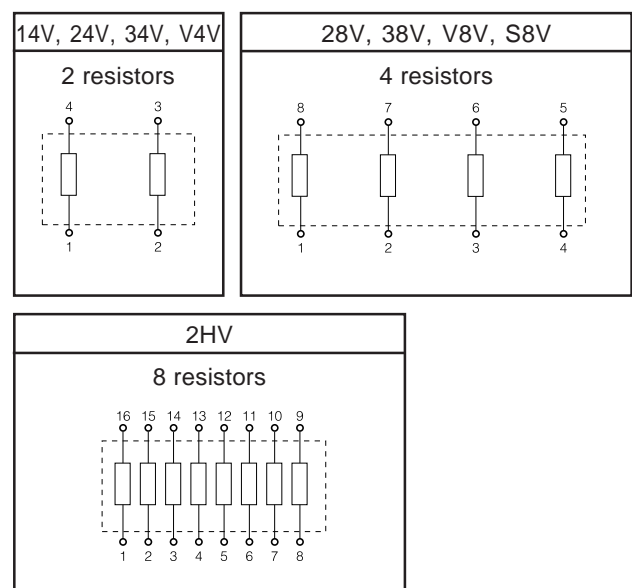


■ Construction (Example : EXBV8V)

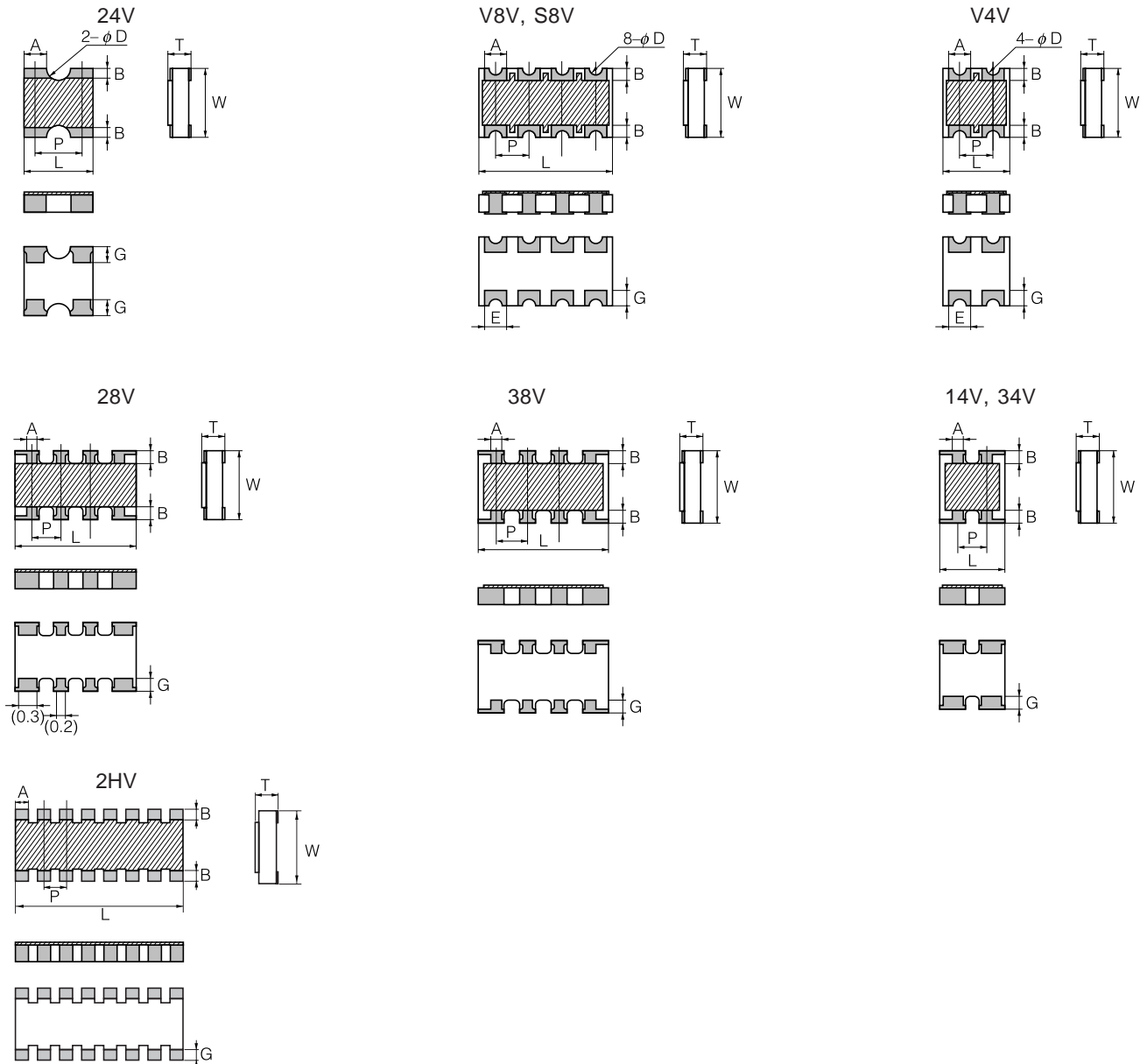


■ Schematics

- Isolated type



■ Dimensions in mm (not to scale)



Type (inches)	Dimensions (mm)								
	L	W	T	A	B	ϕD	P	E	G
EXB14V (0201×2)	0.80±0.10	0.60±0.10	0.35±0.10	0.35±0.10	(0.15±0.10)	—	0.50±0.10	—	0.15±0.10
EXB24V (0402×2)	1.00±0.05	1.00±0.05	0.35±0.05	0.33±0.05	0.15±0.10	0.34±0.05	0.65±0.10	—	0.25±0.05
EXB28V (0402×4)	2.00±0.10	1.00±0.10	0.35±0.10	0.20±0.10	0.20±0.10	—	0.50±0.10	—	0.25±0.10
EXBV4V (0603×2)	1.60±0.20	1.60±0.15	0.60±0.10	0.60±0.10	0.30±0.15	(0.3)	0.80±0.10	0.45±0.10	0.40±0.15
EXB34V (0603×2)	1.60±0.20	1.60±0.15	0.50±0.10	0.45±0.15	(0.30±0.20)	—	0.80±0.15	—	0.30±0.20
EXBV8V (0603×4)	3.20±0.20	1.60±0.15	0.60±0.10	0.60±0.10	0.30±0.15	(0.3)	0.80±0.10	0.45±0.10	0.45±0.15
EXB38V (0603×4)	3.20±0.20	1.60±0.15	0.50±0.10	0.45±0.15	(0.30±0.20)	—	0.80±0.15	—	0.35±0.20
EXBS8V (0805×4)	5.08±0.20	2.20±0.10	0.70±0.20	0.80±0.15	0.50±0.15	(0.5)	1.27±0.20	0.70±0.20	0.55±0.15
EXB2HV (0402×8)	3.80±0.10	1.60±0.10	0.45±0.10	0.30±0.10	(0.30±0.10)	—	0.50±0.10	—	0.30±0.10

() Reference

Design, Specifications are subject to change without notice. Ask factory for technical specifications before purchase and/or use. Whenever a doubt about safety arises from this product, please inform us immediately for technical consultation without fail.

■ Ratings

Item		Specifications
Resistance Range		10 Ω to 1 MΩ: E24 series
Resistance Tolerance		G: ±2 %, J: ±5 %
Number of Terminal	14V,24V,V4V,34V	4 terminal
	28V,38V,V8V,S8V	8 terminal
	2HV	16 terminal
Number of Resistors	14V,24V,V4V,34V	2 resistors
	28V,38V,V8V,S8V	4 resistors
	2HV	8 resistors
Power Rating at 70 °C	14V,28V	0.031 W/element
	24V,V4V,34V,V8V,38V	0.063 W/element
	S8V	0.1 W/element
	2HV	0.063 W/element (0.25 W/package)

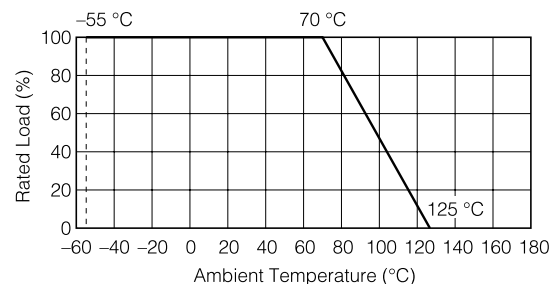
Item		Specifications	
Limiting Element Voltage ⁽¹⁾ (Max. Rated Continuous Working Voltage)	14V	12.5 V	
	2HV	25 V	
	24V,28V,38V,34V,V4V,V8V	50 V	
	S8V	100 V	
Max. Over-load Voltage ⁽²⁾	14V	25 V	
	2HV	50 V	
	24V,28V,38V,34V,V4V,V8V	100 V	
	S8V	200 V	
T.C.R.		±200 ×10 ⁻⁶ /°C(ppm/°C)	
Category Temperature Range (Operating Temperature Range)		-55 °C to 125 °C	
Jumper Array	Rated Current	14V	0.5 A
		2HV,24V,28V,38V,34V,V4V,V8V	1 A
		S8V	2 A
	Max. Overload Current	14V	1 A
		2HV,24V,28V,38V,34V,V4V,V8V	2 A
		S8V	4 A

(1) Rated Continuous Working Voltage (RCWV) should be determined from $RCWV = \sqrt{\text{Power Rating} \times \text{Resistance Value}}$, or Limiting Element Voltage (max. RCWV) listed above, whichever is less.

(2) Overload (Short-time Overload) Test Voltage (SOTV) should be determined from $SOTV = 2.5 \times \text{Power Rating}$ or max. Overload (Voltage) listed above whichever is less.

Power Derating Curve

For resistors operating in ambient temperature above 70 °C, power rating should be derated in accordance with the right figure.



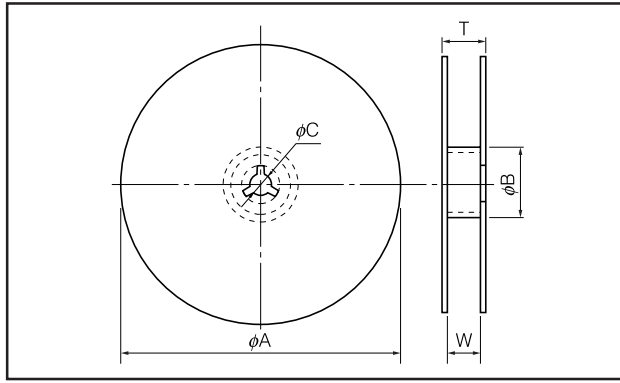
■ Packaging Specifications

● Standard Quantity

Type (inches)	Thickness (mm)	Weight/1000 pcs. (g)	Punched (Paper) Taping	Embossed Taping
EXB14V (0201×2)	0.35	14V: 0.5	10000 pcs./reel	—
EXB24V, 28V (0402×2, 0402×4)	0.35	24V: 1.2 28V: 2	10000 pcs./reel	—
EXBV4V, V8V (0603×2, 0603×4)	0.6	V4V: 5 V8V: 10	5000 pcs./reel	—
EXB34V, 38V (0603×2, 0603×4)	0.5	34V: 3.5 38V: 7	5000 pcs./reel	—
EXBS8V (0805×4)	0.7	S8V: 30	—	2500 pcs./reel
EXB2HV (0402×8)	0.45	2HV: 9	5000 pcs./reel	—

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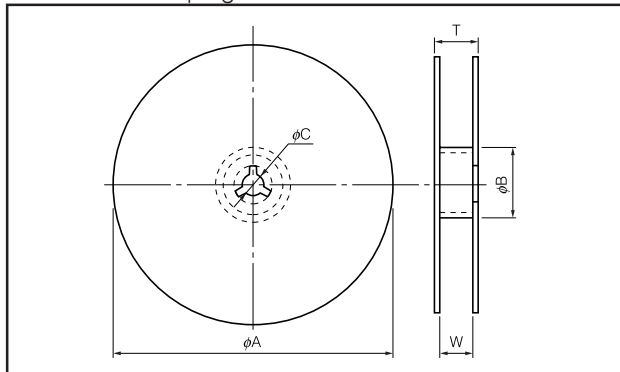
● Punched (Paper) Taping Reel



Dimensions (mm)	Type	φA	φB	φC
Dimensions (mm)	14V, 2HV	180.0 ⁰ _{-3.0}	60 min.	13.0±1.0
	24V, 28V			
	V4V, 34V			
	V8V, 38V			

Dimensions (mm)	Type	W	T
Dimensions (mm)	14V, 2HV	9.0±1.0	11.4±2.0
	24V, 28V		
	V4V, 34V		
	V8V, 38V		

● Embossed Taping Reel

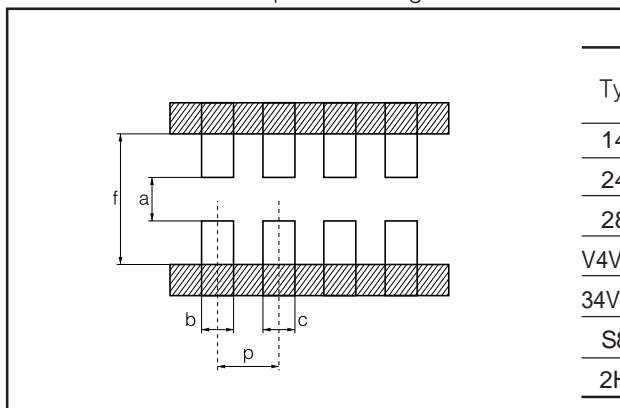


Dimensions (mm)	Type	φA	φB	φC
Dimensions (mm)	S8V	180.0 ⁰ _{-3.0}	60 min.	13.0±1.0

Dimensions (mm)	Type	W	T
Dimensions (mm)	S8V	13.0±1.0	15.4±2.0

■ Land pattern design

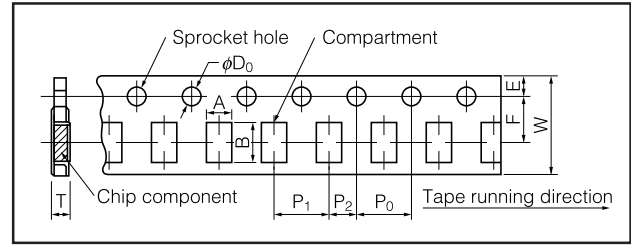
Recommended land pattern design for Network chip is shown below.



Type	Dimensions				
	a	b	c	p	f
14V	0.3	0.3	0.3	0.50	0.9
24V	0.5	0.35 to 0.40	0.35 to 0.40	0.65	1.4 to 1.5
28V	0.4	0.525	0.25	0.50	1.4
V4V, V8V	0.7 to 0.9	0.4 to 0.45	0.4 to 0.45	0.80	2 to 2.4
34V, 38V	0.7 to 0.9	0.4 to 0.5	0.4 to 0.5	0.80	2.2 to 2.6
S8V	1 to 1.2	0.5 to 0.75	0.5 to 0.75	1.27	3.2 to 3.8
2HV	1	0.425	0.25	0.50	2

Design, Specifications are subject to change without notice. Ask factory for technical specifications before purchase and/or use. Whenever a doubt about safety arises from this product, please inform us immediately for technical consultation without fail.

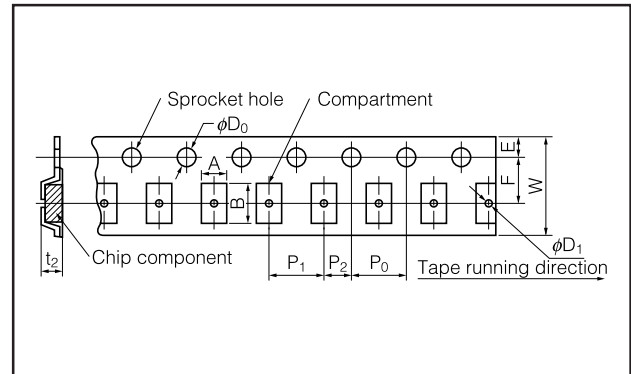
● Punched (Paper) Taping



Dimensions (mm)	Type	A	B	W	F	E
	14V	0.70±0.05	0.90±0.05	8.00±0.20	3.50±0.05	1.75±0.10
	24V	1.20±0.05	1.20±0.05			
	28V		2.20±0.10			
	V4V	1.95±0.15	1.95±0.20			
	34V	2.00±0.15	3.60±0.20			
	V8V					
38V	1.90±0.15	4.10±0.15				
2HV						

Dimensions (mm)	Type	P1	P2	P0	φD0	T
	14V	2.00±0.10		4.00±0.10	1.50 ^{+0.10} ₀	0.52±0.05
	24V					
	28V					
	V4V	2.00±0.05		4.00±0.10	1.50 ^{+0.10} ₀	0.84±0.05
	34V					0.70±0.05
	V8V	4.00±0.10				0.84±0.05
	38V					
	2HV					0.70±0.05

● Embossed Taping



Dimensions (mm)	Type	A	B	W	F	E	P0
Dimensions (mm)	S8V	2.80±0.20	5.70±0.20	12.00±0.30	5.50±0.05	1.75±0.10	4.00±0.10

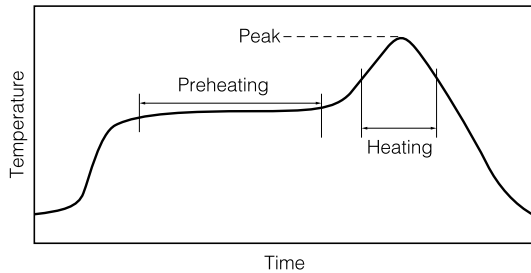
Dimensions (mm)	Type	P1	P2	φD0	t2	φD1
Dimensions (mm)	S8V	4.00±0.10	2.00±0.05	1.50 ^{+0.10} ₀	1.6 max.	1.50 ^{+0.10} ₀

■ **Recommended Soldering Conditions**

Recommendations and precautions are described below.

● **Recommended soldering conditions for reflow**

- Reflow soldering should be a maximum of two times
- Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminations and study every type of the printed circuit board for solderability, before actual use.



● **Flow soldering**

- Flow soldering is not recommended because solder bridge may occur.

For solder (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free solder (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

⚠ **Safety Precautions**

1. **Component Placement**

- ① Take measures against mechanical stress during and after mounting, so as not to damage the termination and protective coating.
- ② Misplacement of components on the land pattern may cause solder bridge problem.
2. If transient load (heavy load in a short time) like pulse is expected to be applied, carry out evaluation and confirmation test with the resistors actually mounted on the board before using in production.
When the load of more than rated power is applied under the load condition at steady state, it may impair performance and/or reliability of resistor. Never exceed the rated power.
3. Chlorine type or other high-activity flux is not recommended as the residue may affect performance or reliability of resistors.
4. When soldering with soldering iron, never touch the body of the chip resistor with the tip of the soldering iron. When using a soldering iron with a tip at high temperature, solder for as short a time as possible (three seconds or less up to 350 °C).
5. Avoid physical shock to the resistor and nipping of the resistor with hard tool (pliers or tweezers) as it may damage protective film or the body of resistor and may affect resistor's performance.
6. Do not use the product in high humidity atmospheres.